

**PATENT ASSIGNMENT**

Electronic Version v1.1  
 Stylesheet Version v1.1

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
Tomoaki Abe	11/14/2011
Kaori Namioka	11/14/2011
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	Stanley Electric Co., Ltd.
<b>Street Address:</b>	2-9-13 Nakameguro, Meguro-ku
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<b>Postal Code:</b>	153-8636
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	13270076
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<b>Total Attachments: 2</b>	
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**ASSIGNMENT**

WHEREAS WE, the below named inventors, [hereinafter referred to as Assignors], have made an invention entitled:

**METHOD FOR MANUFACTURING CERAMIC MULTI-LAYERED INTERCONNECTION SUBSTRATE**

for which WE executed an application for United States Letters Patent concurrently herewith and for which WE filed Japanese Patent Application No. 2010-228468 on October 8, 2010; and

WHEREAS STANLEY ELECTRIC CO., LTD., a corporation of Japan, whose post office address is 2-9-13 Nakameguro, Meguro-ku, Tokyo 153-8636 Japan (hereinafter referred to as Assignee), is desirous of securing the entire right, title, and interest in and to this invention in all countries throughout the world, and in and to the application of United States Letters Patent on this invention and the Letters Patent to be issued upon this application;

NOW THEREFORE, be it known that, for and in consideration of the sum of One Dollar (\$1.00) in hand paid and other good and valuable consideration the receipt of which from Assignee is hereby acknowledged, WE, as assignors, have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the Assignee, its lawful successors and assigns, OUR entire right, title, and interest in and to this invention and this application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof, and all rights to claim priority on the basis of such applications, and all applications for Letters Patent which may hereafter be filed for this invention in any foreign country and all Letters Patent which may be granted on this invention in any foreign country, and all extensions, renewals, and reissues thereof; and WE hereby authorize and request the Commissioner of Patents and Trademarks of the United States and any official of any foreign country whose duty it is to issue patents on applications as described above, to issue all Letters Patent of this invention to Assignee, its successors and assigns, in accordance with the terms of this Assignment;

AND, WE HEREBY covenant that WE have the full right to convey the interest assigned by this Assignment, and WE have not executed and will not execute any agreement in conflict with this Assignment;

AND, WE HEREBY further covenant and agree that WE will, without further consideration, communicate with Assignee, its successors and assigns, any facts known to US respecting this invention, and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver any and all papers that may be necessary or desirable to perfect the title to this invention in said Assignee, its successors or assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid Assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States and any foreign country, it being understood that any expense incident to the execution of such papers shall be borne by the Assignee, its successors and assigns;

AND, WE HEREBY authorize and request the attorneys WE have empowered in the Declaration and Power of Attorney in this application, to insert here in parentheses (Application No. 13/270,076, filed October 10, 2011) the filing date and application number of said application when known.

IN TESTIMONY WHEREOF, I have hereunto set my hand.

<u>Full Name of First Assignor</u> Tomoaki ABE	<u>Assignor's Signature</u> <i>Tomoaki Abe</i>	<u>Date</u> November 14, 2011
<u>Address:</u> c/o Stanley Electric Co., Ltd. 2-9-13, Nakameguro, Meguro-ku, Tokyo 153-8636 Japan		<u>Citizenship</u> Japan
Names of additional inventors attached <input checked="" type="checkbox"/> Yes <input type="checkbox"/> No		

KENEALY VAIDYA LLP

<u>Full Name of Second Assignor</u> Kaori NAMIOKA	<u>Assignor's Signature</u> <i>Kaori Namioka</i>	<u>Date</u> <i>November 14, 2011</i>
<u>Address:</u> c/o Stanley Electric Co., Ltd. 2-9-13, Nakameguro, Meguro-ku, Tokyo 153-8636 Japan		<u>Citizenship</u> Japan
<p>Names of additional inventors attached      <input type="checkbox"/> Yes      <input checked="" type="checkbox"/> No</p>		

KENEALY VAIDYA LLP